

SECTION 27 05 26 GROUNDING AND BONDING FOR COMMUNICATIONS SYSTEMS

PART 1 - GENERAL

1.1 DESCRIPTION

- A. This section identifies common and general grounding and bonding requirements of communication installations and applies to all sections of Divisions 27 and 28.

1.2 RELATED WORK

- A. Low voltage wiring: Section 26 05 19, LOW VOLTAGE ELECTRICAL POWER CONDUCTORS AND CABLES.

1.3 SUBMITTALS

- A. Submit in accordance with Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS.
- B. Provide plan indicating location of system grounding electrode connections and routing of aboveground and underground grounding electrode conductors.
- C. Closeout Submittals: In addition to Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS provide the following:
 - 1. Certified test reports of ground resistance.
 - 2. Certifications: Two weeks prior to final inspection, submit following to COR:
 - a. Certification materials and installation is in accordance with construction documents.
 - b. Certification complete installation has been installed and tested.

PART 2 - PRODUCTS

2.1 COMPONENTS

- A. Grounding and Bonding Conductors:
 - 1. Provide UL 83 insulated stranded copper equipment grounding conductors, with the exception of solid copper conductors for sizes 6 mm² (10 AWG) and smaller. Identify all grounding conductors with continuous green insulation color, except identify wire sizes 25 mm² (4 AWG) and larger per NEC.
 - 2. Provide ASTM B8 bare stranded copper bonding conductors, with the exception of ASTM B1 solid bare copper for wire sizes 6 mm² (10 AWG) and smaller.

- B. Ground Rods:
 - 1. Copper clad steel, 19 mm (3/4-inch) diameter by 3000 mm (10 feet) long, conforming to UL 467.
 - 2. Provide quantity of rods required to obtain specified ground resistance.
- C. Splices and Termination Components: Provide components meeting or exceeding UL 467 and clearly marked with manufacturer's name, catalog number, and permitted conductor sizes.
- D. Telecommunication System Ground Busbars:
 - 1. Telecommunications Main Grounding Busbar (TMGB):
 - a. 6.4 mm (1/4 inch) thick solid copper bar.
 - b. Minimum 100 mm (4 inches) high and length sized in accordance application requirements and future growth of minimum 510 mm (20 inches) long.
 - c. Minimum thirty predrilled attachment points (two rows of fifteen each) for attaching standard sized two-hole grounding lugs.
 - 1) 27 lugs with 15.8 mm (5/8 inch) hole centers.
 - 2) 3 lugs with 25.4 mm (1 inch) hole centers.
 - d. Wall-mount stand-off brackets, assembly screws and insulators for 100 mm (4 inches) standoff from wall.
 - e. Listed as grounding and bonding equipment.
 - 2. Telecommunications Grounding Busbar (TGB):
 - a. 6.4 mm (1/4 inch) thick solid copper bar.
 - b. Minimum 50 mm (2 inches) high and length sized in accordance application requirements and future growth of minimum 300 mm long (12 inches) long.
 - c. Minimum nine predrilled attachment points (one row) for attaching standard sized two-hole grounding lugs.
 - 1) 6 lugs with 15.8 mm (5/8 inch) hole centers.
 - 2) 3 lugs with 25.4 mm (1 inch) hole centers.
 - d. Wall-mount stand-off brackets, assembly screws and insulators for 100 mm (4 inches) standoff from wall.
 - e. Listed as grounding and bonding equipment.
- E. Equipment Rack and Cabinet Ground Bars:
 - 1. Solid copper ground bars designed for horizontal mounting to framework of open racks or enclosed equipment cabinets:

- a. 4.7 mm (3/16 inch) thick by 19.1 mm (3/4 inch) high hard-drawn electrolytic tough pitch 110 alloy copper bar.
 - b. 482 mm (19 inches) or 584 mm (23 inches) EIA/ECA-310-E rack mounting width (as required) for mounting on racks or cabinets.
 - c. Eight 6-32 tapped ground mounting holes on 25.4 mm (1 inch) intervals.
 - d. Four 7.1 mm (0.281 inch) holes for attachment of two-hole grounding lugs.
 - e. Copper splice bar of same material to transition between adjoining racks.
 - f. Two each 12-24 x 19.1 mm (3/4 inch) copper-plated steel screws and flat washers for attachment to rack or cabinet.
 - g. Listed as grounding and bonding equipment.
2. Solid copper ground bars designed for vertical mounting to framework of open racks or enclosed equipment cabinets:
- a. 1.3 mm (0.05 inch) thick by 17 mm (0.68 inch) wide tinned copper strip.
 - b. 1997 mm (78 inches) high for mounting vertically on full height racks.
 - c. Holes punched on 15.875 mm-15.875 mm-12.7 mm (5/8"-5/8"-1/2") alternating vertical centers to match EIA/ECA-310-E Universal Hole Pattern for a 45 RMU rack.
 - d. Three #12-24 zinc-plated thread forming hex washer head installation screws, an abrasive pad and antioxidant joint compound.
 - e. NRTL listed as grounding and bonding equipment.
- F. Ground Terminal Blocks: Provide screw lug-type terminal blocks at equipment mounting location (e.g. backboards and hinged cover enclosures) where rack-type ground bars cannot be mounted.
1. Electroplated tin aluminum extrusion.
 2. Accept conductors ranging from #14 AWG through 2/0.
 3. Hold conductors in place by two stainless steel set screws.
 4. Two 6 mm (1/4 inch) holes spaced on 15.8 mm (5/8 inch) centers to allow secure two-bolt attachment.
 5. Listed as a wire connector.
- G. Splice Case Ground Accessories: Provide splice case grounding and bonding accessories manufactured by splice case manufacturer when

available. Otherwise, use 16 mm² (6 AWG) insulated ground wire with shield bonding connectors.

- H. Irreversible Compression Lugs:
 - 1. Electroplated tinned copper.
 - 2. Two holes spaced on 15.8 mm (5/8 inch) or 25.4 mm (1 inch) centers.
 - 3. Sized to fit the specific size conductor.
 - 4. Listed as wire connectors.
- I. Antioxidant Joint Compound: Oxide inhibiting joint compound for copper-to-copper, aluminum-to-aluminum or aluminum-to-copper connections.

PART 3 - EXECUTION

3.1 EQUIPMENT INSTALLATION AND REQUIREMENTS

- A. Exterior Equipment Grounding: Bond exterior metallic components (including masts and cabinets), antennas, satellite dishes, towers, raceways, primary telecommunications protector/arresters, secondary surge protection, waveguides, cable shields, down conductors and other conductive items to directly to Intersystem Bonding Termination.
- B. Install telecommunications bonding backbone conductor throughout building via telecommunications backbone pathways effectively bonding all interior telecommunications grounding busbars in telecommunications rooms, to telecommunications main grounding busbar in Demarc room after testing bond to verify bonding conductor for telecommunications from grounding electrode conductor is installed per NEC. Size telecommunications bonding backbone conductor as specified in TIA-607-B.
- C. Inaccessible Grounding Connections: Utilize exothermic welding for bonding of buried or otherwise inaccessible connections with the exception of connections requiring periodic testing.
- D. Conduit Systems:
 - 1. Bond ferrous metallic conduit to ground.
 - 2. Bond grounding conductors installed in ferrous metallic conduit at both ends of conduit using grounding bushing with #6 AWG conductor.
- E. Boxes, Cabinets, and Enclosures:
 - 1. Bond each pull box, splice box, equipment cabinet, and other enclosures through which conductors pass (except for special grounding systems for intensive care units and other critical units shown) to ground.
 - 2. Raised Floors: Bonding raised floor components to ground.

- F. Corrosion Inhibitors: Apply corrosion inhibitor for protecting connection between metals used to contact surfaces, when making ground and ground bonding connections.
- G. Telecommunications Grounding System:
 - 1. Bond telecommunications grounding systems and equipment to facility's electrical grounding electrode at Intersystem Bonding Termination.
 - 2. Provide hardware as required to effectively bond metallic cable shields communications pathways, cable runway, and equipment chassis to ground.
 - 3. Install bonding conductors without splices using shortest length of conductor possible to maintain clearances required by NEC.
 - 4. Provide paths to ground that are permanent and continuous with a resistance of 1 ohm or less from each raceway, cable tray, and equipment connection to telecommunications grounding busbar.
 - 5. Below-Grade Connections: When making exothermic welds, wire brush or file the point of contact to a bare metal surface. Use exothermic welding cartridges and molds in accordance with manufacturer's recommendations. After welds have been made and cooled, brush slag from weld area and thoroughly clean joint areas. Notify COR prior to backfilling at ground connections.
 - 6. Above-Grade Bolted or Screwed Grounding Connections:
 - a. Remove paint to expose entire contact surface by grinding.
 - b. Clean all connector, plate and contact surfaces.
 - c. Apply corrosion inhibitor to surfaces before joining.
 - 7. Bonding Jumpers:
 - a. Assemble bonding jumpers using insulated ground wire of size and type shown on drawings or use a minimum of 16 mm² (6 AWG) insulated copper wire terminated with compression connectors of proper size for conductors.
 - b. Use connector manufacturer's compression tool.
 - 8. Bonding Jumper Fasteners:
 - a. Conduit: Connect bonding jumpers using lugs on grounding bushings or clamp pads on push-type conduit fasteners. Where appropriate, use zinc-plated external tooth lockwashers or Belleville Washers.
 - b. Wireway and Cable Tray: Fasten bonding jumpers using zinc-plated bolts, external tooth lockwashers or Belleville washers and nuts. Install protective cover, e.g., zinc-plated

- acorn nuts, on bolts extending into wireway or cable tray to prevent cable damage.
 - c. Grounding Busbars: Fasten bonding conductors using two-hole compression lugs. Use 300 series stainless steel bolts, Belleville Washers, and nuts.
 - d. Slotted Channel Framing and Raised Floor Stringers: Fasten bonding jumpers using zinc-plated, self-drill screws and Belleville washers or external tooth lock washers.
- H. Telecommunications Room Bonding:
- 1. Telecommunications Grounding Busbars:
 - a. Install busbar hardware no less than 950 mm (18 inches) A.F.F.
 - b. Where other grounding busbars are located in same room, e.g. electrical panelboard for telecommunications equipment, bond busbars together as indicated on grounding riser diagrams.
 - c. Make conductor connections with two-hole compression lugs sized to fit busbar and conductors.
 - d. Attach lugs with stainless steel hardware after preparing bond according to manufacturer recommendations and treating bonding surface on busbar with anti-oxidant to help prevent corrosion.
 - 2. Telephone-Type Cable Rack Systems:
 - a. Aluminum pan installed on telephone-type cable rack serves as primary ground conductor within communications room.
 - b. Make ground connections by installing bonding jumpers:
 - 1) Install minimum 16 mm² (6 AWG) bonding between telecommunications ground busbars and the aluminum pan installed on cable rack.
 - 2) Install 16 mm² (6 AWG) bonding jumpers across aluminum pan junctions.
- I. Self-Supporting and Cabinet-Mounted Equipment Rack Ground Bars:
- 1. Install rack-mount horizontal busbar or vertical busbar to provide multiple bonding points,
 - 2. At each rack or cabinet containing active equipment or shielded cable terminations:
 - a. Bond busbar to ground as part of overall telecommunications bonding and grounding system.

- b. Bond copper ground bars together using solid copper splice plates manufactured by same ground bar manufacturer, when ground bars are provided at rear of lineup of bolted together equipment racks.
 - c. Bond non-adjacent ground bars on equipment racks and cabinets with 16 mm² (6 AWG) insulated copper wire bonding jumpers attached at each end with compression-type connectors and mounting bolts.
 - d. Provide 16 mm² (6 AWG) bonding jumpers between rack and cabinet ground busbars and overhead cable runway or raised floor stringers, as appropriate.
- J. Backboards: Provide a screw lug-type terminal block or drilled and tapped copper strip near top of backboards used for communications cross-connect systems. Connect backboard ground terminals to cable runway using an insulated 16 mm² (6 AWG) bonding jumper.
- K. Other Communication Room Ground Systems: Ground metallic conduit, wireways, and other metallic equipment located away from equipment racks or cabinets to cable tray or telecommunications ground busbar, whichever is closer, using insulated 16 mm² (6 AWG) ground wire bonding jumpers.
- L. Communications Cable Grounding:
 - 1. Bond all metallic cable sheaths in multi-pair communications cables together at each splicing or terminating location to provide 100 percent metallic sheath continuity throughout communications distribution system.
 - 2. Install a cable shield bonding connector with a screw stud connection for ground wire, at terminal points. Bond cable shield connector to ground.
 - 3. Bond all metallic cable shields together within splice closures using cable shield bonding connectors or splice case manufacturer's splice case grounding and bonding accessories. When an external ground connection is provided as part of splice closure, connect to an effective ground source and bond all other metallic components and equipment at that location.
- M. Communications Cable Tray Systems:
 - 1. Bond metallic structures of cable tray to provide 100 percent electrical continuity throughout cable tray systems.
 - 2. Where metallic cable tray systems are mechanically discontinuous:
 - a. Install splice plates provided by cable tray manufacturer between cable tray sections so resistance across a bolted

connection is 0.010 ohms or less, as verified by measuring across splice plate connection.

- b. Install 16 mm² (6 AWG) bonding jumpers across each cable tray splice or junction where splice plates cannot be used.
 3. Bond cable tray installed in same room as telecommunications grounding busbar to busbar.
- N. Communications Raceway Grounding:
1. Conduit: Use insulated 16 mm² (6 AWG) bonding jumpers to bond metallic conduit at both ends and intermediate metallic enclosures to ground.
 2. Cable Tray Systems: Use insulated 16 mm² (6 AWG) grounding jumpers to bond cable tray to column-mounted building ground plates (pads) at both ends and approximately 16 meters (50 feet) on centers.
- O. Ground Resistance:
1. Install telecommunications grounding system so resistance to grounding electrode system measures 5 ohms or less.
 2. Measure grounding electrode system resistance using an earth test meter, clamp-on ground tester, or computer-based ground meter as defined in IEEE 81. Record ground resistance measurements before electrical distribution system is energized.
 3. Backfill only after below-grade connection have been visually inspected by COR. Notify COR twenty-four hours before below-grade connections are ready for inspection.

3.2 FIELD QUALITY CONTROL

- A. Perform tests per BICSI's Information Technology Systems Installation Methods Manual (ITSIMM), Recommended Testing Procedures and Criteria.
- B. Perform two-point bond test using trained installers qualified to use test equipment.
- C. Conduct continuity test to verify that metallic pathways in telecommunications spaces are bonded to TGB or TMGB.
- D. Conduct electrical continuity test to verify that TMGB is effectively bonded to grounding electrode conductor.
- E. Visually inspect to verify that screened and shielded cables are bonded to TGB or TMGB.
- F. Perform a resistance test to ensure patch panel, rack and cabinet bonding connection resistance measures less than 5 Ohms to TGB or TMGB.

END OF SECTION 27 05 26